

Viking eUSB

Embedded USB Manual

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Industrial Products

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Revision History

Date	Revision	Description
A	9/12/14	Initial release VRFDUC3(L)032GYCNxx PN for SM3252 VRFDUC3032GYCNE1 (12/13/2013) Update PN table for new PN's and 16GB (A1, 6/2/2014) Revised Standby Current and Operating Current based on 3.3V NAND devices (A2, 7/8/14) Removed firmware upgrade capability (A3, 8/8/14)
B	9/16/14	Add VRFDUC31024YCG PN.

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Legal Information

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Ordering Information: eUSB Family

Viking High Performance USB embedded Drive Ordering Information

Part Number Version-1 (four flash placements)	Capacity	Device Density	Voltage	# Devices	Channels	LBA
VRFDUC3(L)1024YxE3yy	1GB	8Gb	3.3	1	2	1,974,672
VRFDUC3(L)2048YxE3yy	2GB	8Gb	3.3	2	2	3,928,176
VRFDUC3(L)4096YxH3yy	4GB	16Gb	3.3	2	2	7,835,184
VRFDUC3(L)8192YxK3yy	8GB	32Gb	3.3	2	2	15,649,200
VRFDUC3(L)016GYxK3yy	16GB	32Gb	3.3	4	2	31,277,232
VRFDUC3(L)032GYxN3yy	32GB	64Gb	3.3	4	2	62,533,296
VRFDUC3(L)1024YCGyy	1GB	8Gb	5	1	1	1,974,672
VRFDUC3(L)2048YxGyy	2GB	8Gb	5	2	2	3,928,176
VRFDUC3(L)4096YxHyy	4GB	16Gb	5	2	2	7,835,184
VRFDUC3(L)8192YxKyy	8GB	32Gb	5	2	2	7,835,184
VRFDUC3(L)016GYxKyy	16GB	32Gb	5	4	2	31,277,232
VRFDUC3(L)032GYxNyy	32G	64Gb	5	4	2	62,533,296

Notes:

1. DUC3xxxx signifies standard profile, DUC3Lxxxx signifies low profile.
2. x = C for Commercial temperature range: 0 to 70°C (32 to 158° F)
or I for Industrial temperature range: -40 to 85°C (-40 to 185° F)
3. Storage capacity listed will vary due to formatting and additional functions,
and therefore is not available for storage.
4. USB's ship formatted from the factory unless otherwise requested.
5. All eUSBs are based on SLC flash unless otherwise requested.
6. All capacities are available in 3.3V versions.
7. yy indicates BOM specific information
8. "L" indicate low profile
9. Maximum of 4KB per page

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1 Introduction

1.1 Product Overview

Viking Technology's Embedded USB (eUSB) module provides a rugged, reliable and cost effective non-volatile memory, solutions to OEM customers in the Communication, Networking, Embedded and Industrial markets. The eUSB module is a secure pluggable device and a drop-in replacement for Intel® Z-U130 Value Solid State Drive with a USB 2.0 interface, ECC and global wear-leveling. Additional options such as MLC (Multi Level Cell) technology and ESD protection are also available.

Viking's rugged industrial designed USB's offer the highest flash storage reliability and performance in harsh environments such as shock, vibration, humidity, altitude, ESD, and extreme temperatures. Viking USB's meet JEDEC JESD22 standards and pass numerous qualifications including MIL-STDs and NEBS.

Viking can also provide specialized services to OEMs designing customized hardware and systems by offering:

- Locked BOM control with customer product change notification (PCN)
- Pre-installed software, custom software imaging and ID strings
- Custom packaging and labeling
- Comprehensive supply-chain management
- Customer specified testing
- 30k volt ESD protection
- Conformal coating
- Localized Field Application Engineering for complete pre and post sale technical support

1.2 Features

The embedded USB drive delivers the following features:

- USB 2.0 high speed compatible (supports Bulk-Only transport protocol)*
- Up to 35 MB/s Read Speed and 23 MB/s Write Speed (Dual Channel)
- Up to 23 MB/s Read Speed and 12 MB/s Write Speed (Single Channel)
- Host Interface Speed 60MB/s
- Drive Activity indicator signal
- Low power Dissipation- less than 0.45W active; less than 1mW standby

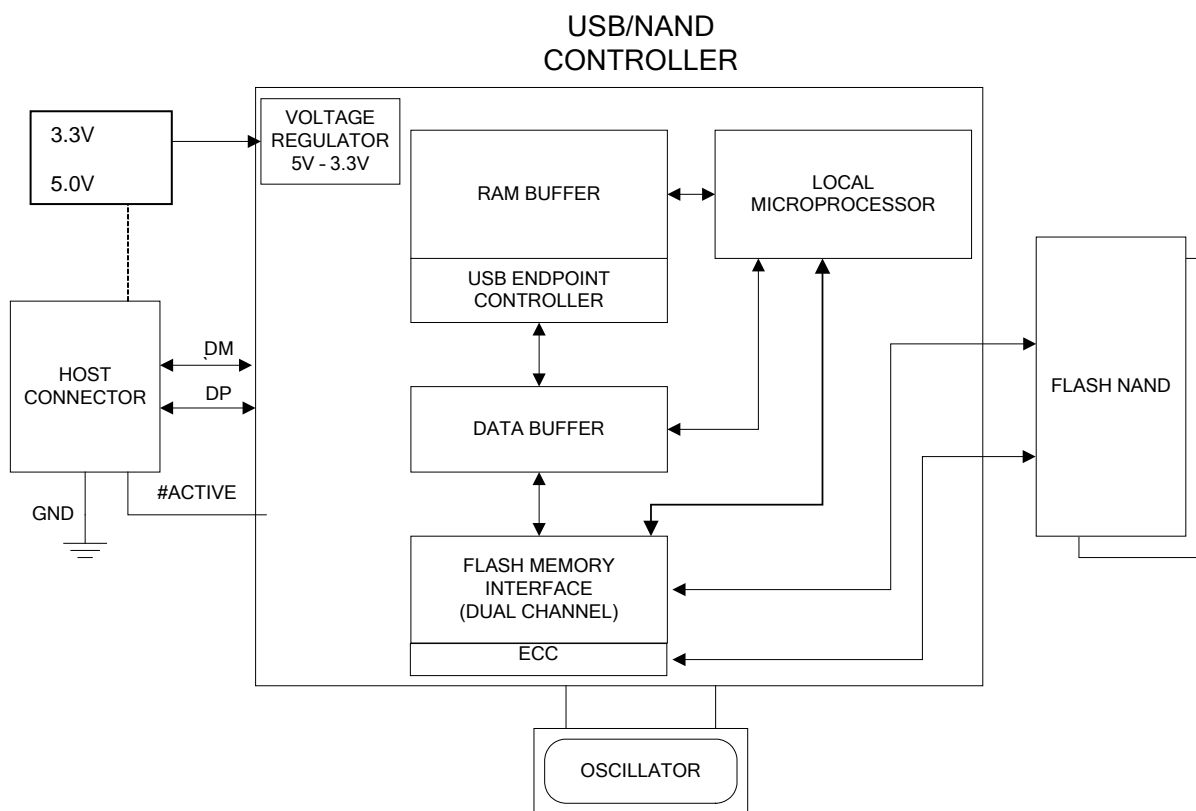
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- Solid state, Non-volatile NAND Memory
- RoHS Compliant
- Static Wear Leveling

* With exception of 3.3V only operation, USB specification is 5V.

1.3 Block Diagram

Figure 1-1: High-Level Block Diagram



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1.4 USB Interface

- The USB interface is compliant with the USB 2.0 specification.
- The USB interface connects the host computer to the embedded USB.
- The USB interface runs at a maximum speed of 2.0 Gbps (gigabits per second). If the host computer is unable to negotiate a speed of 2.0 Gbps, the USB interface automatically renegotiates to lower speeds.

2 Product Specifications

2.1 Performance

The host interface speed is 60MB/s with a read/write bandwidth shown in the following tables.

Table 2-1: Maximum Sustained Read and Write Bandwidth

Access Type	MB/s
Read, Dual Channel	Up to 35
Write, Dual Channel	Up to 23

2.2 Timing

Table 2-2: Timing Specifications

2.3 Power-up AC timing Requirements

Parameter	Symbol	Min.	Typical	Max.	Unit
Powerup to Ready (from 2.7V VBUS)	tRESET	100	150	250	ms

Notes:

1. This power-up timing can be changed to 10ms upon request. The long power-up delay is designed to accommodate slow power-up times of rack systems.

2.4 Electrical Characteristics

2.4.1 Absolute Maximum Ratings

Table 2-3: Absolute Maximum Ratings

Parameter	Symbol	Value	Unit
5.0 Supply Voltage	VBUS	-0.3 ~ 5.5	V
3.3 Supply Voltage	VBUS	-0.3 ~ 4.0	V
Input Voltage	VIN	GND - 0.5 ~ VCC + 0.5	V
Storage Temperature	TST	-55 ~ 150	°C

Notes:

1. Permanent device damage may occur if 'ABSOLUTE MAXIMUM RATINGS' are exceeded. Functional operation should be restricted to recommended operating condition. Exposure to higher than recommended voltage for extended periods of time could affect device reliability.

2.4.2 DC Operating Conditions and Characteristics

Table 2-4: Voltage and Current Ratings

Parameter		Symbol	Min.	Typical	Max.	Unit
5.0 Supply voltage ($\pm 5\%$)		VBUS	4.75	5.0	5.25	V
3.3 Supply voltage ($\pm 5\%$)		VBUS	3.14	3.3	3.465	V
Regulated Output Voltage (internal eUSB voltage)		VDD33O	2.9	3.3	3.6	V
Input high voltage		VIH	2.0	-	-	V
Input low voltage		VIL	-	-	0.8	V
Output high voltage		VOH	2.4	-		V
Output low voltage		VOL	-	-	0.4	V
Standby Current ²	1 Flash Device	I _{STB}	-	16.5 + 6.6	23.1 + 33	μA
	2 Flash Devices		-	16.5 + 13.2	23.1 + 66	μA
	4 Flash Devices		-	16.5 + 19.8	23.1 + 132	μA
Operating Current ²	1 Flash Device	I _{OP}	-	132 + 9.9	165 + 19.8	mA
	2 Flash Devices		-	132 + 19.8	165 + 39.6	mA
	4 Flash Devices		-	132 + 39.6	165 + 79.2	mA

Notes:

1. Recommended operating conditions (Voltages referenced to GND, TA = 0 to 70°C)
2. Based on 3.3V NAND

2.4.3 Power Consumption

All onboard power requirements of the eUSB are derived from the 5V or 3.3V input rail.

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Table 2-5: Power Consumption

Power	Typical	units
Standby	1	mW
Operating	450	mW

2.4.4 Capacitance

Table 2-6: Bus Line Capacitance

Parameter	Symbol	Min	Max	Unit
Bus line capacitance	C _L	-	20	pF

2.5 Environmental Conditions

2.5.1 Temperature and Altitude

Table 2-7: Temperature and Altitude Related Specifications

Conditions	Operating	Shipping	Storage
Commercial Temperature	0 to 70°C (32 to 158° F)	-40 to 85°C (-40 to 185° F)	-40 to 85°C (-40 to 185° F)
Industrial Temperature¹	-40 to 85°C (-40 to 185° F)	-40 to 85°C (-40 to 185° F)	-40 to 85°C (-40 to 185° F)
Humidity (non-condensing)	5% to 95%	5% to 95%	5% to 95%
Max Temperature Gradient	20°C/Hour (36°F/Hour)	n/a	n/a
Altitude	-304.8 to 24,384 m (-1,000 to 80,000 ft)	-304.8 to 24,384 m (-1,000 to 80,000 ft)	-304.8 to 24,384 m (-1,000 to 80,000 ft)
Storage Time Duration	n/a	n/a	1 year

Notes:

1. SLC flash based products are available in the following temperature ranges:
 - a) Commercial temperature range of 0 to 70°C (32 to 158° F)
 - b) Industrial temperature range -40 to 85°C (-40 to 185° F)

2.6 Reliability

Table 2-8: Reliability Specifications

Parameter	Value
Mean Time Between Failures (MTBF) ¹	2,500,000 hours
Power On/Off Cycles ²	50,000 cycles

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Parameter	Value
Read Endurance	Unlimited
Write or Erase Endurance ³	(specified by the flash component)
Wear-leveling	Global
Data retention	>10 years

Notes:

1. MTBF is calculated based on a Part Stress Analysis. It assumes nominal voltage, with all other parameters within specified range. Telcordia method SR-332 component FIT rate at 55°C.
2. Power On/Off Cycles defined as power being removed from the drive, and then restored. Note that host systems and drive enclosures may remove power from the drive for reasons other than a system shutdown.
3. SLC NAND has a higher endurance than MLC NAND

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3 Mechanical Information

The dimensions of the eUSB (version-1) are based on the following
PCB #s: 1208, 1209

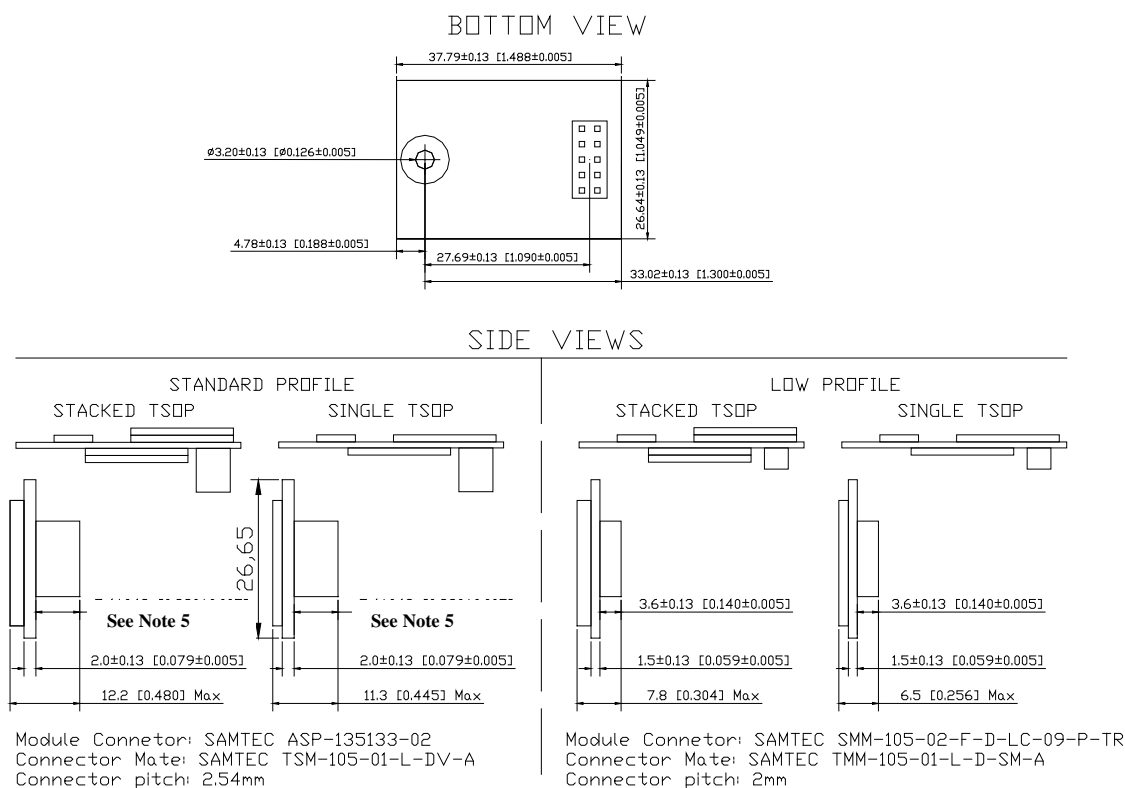
As an example, the 1208 PCB would have a 0001208A marking that is silkscreened at the bottom edge of the PCB near the mounting hole on the same side as the connector (at bottom side of the eUSB) as shown in the following figure.

Figure 3-1: Location of PCB # marking



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Figure 3-2: Dimensions (Version-1)



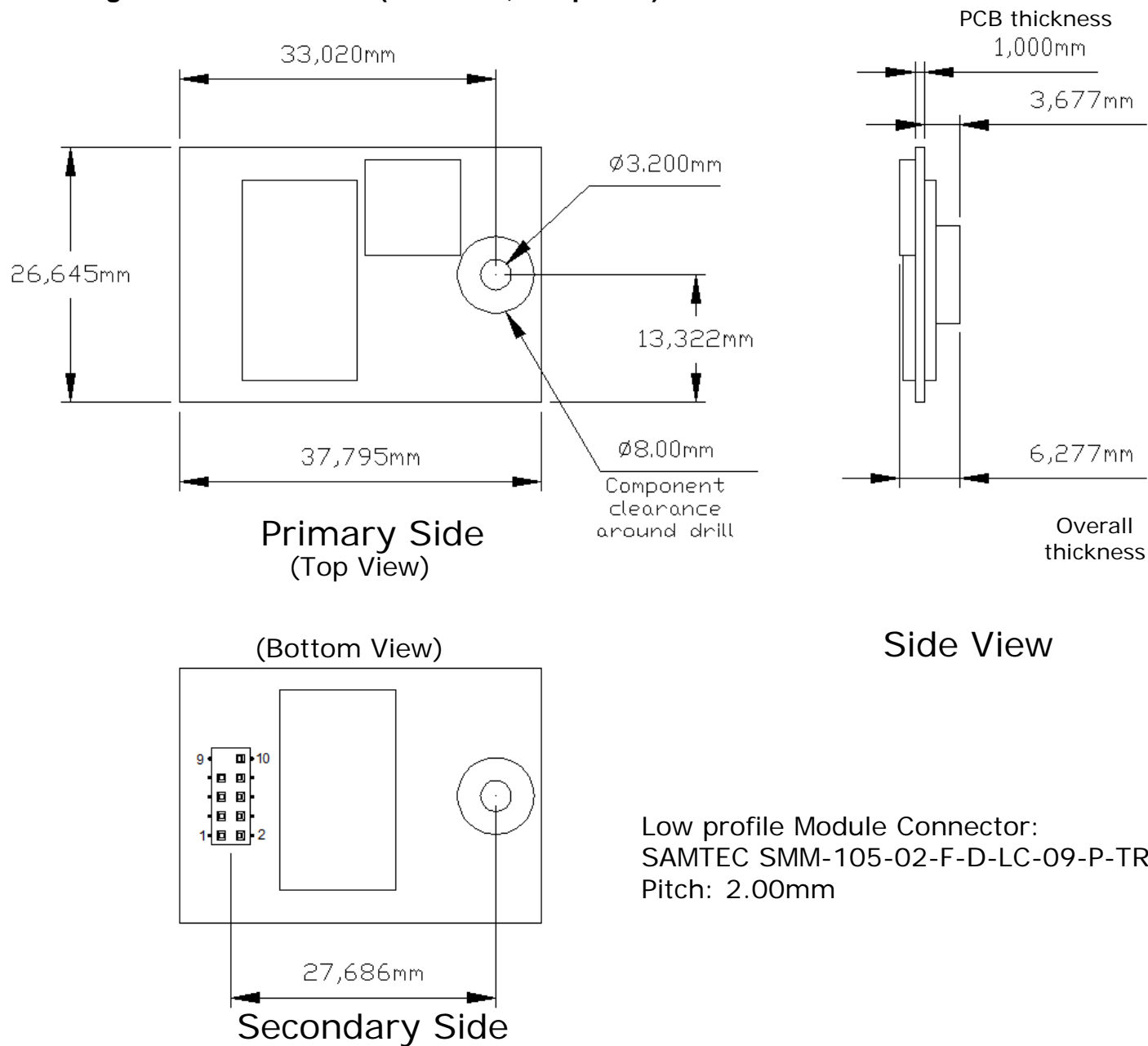
Notes:

1. PCB number is silkscreened on the PCB
2. Dimensions shown in millimeters [inches]
3. Max screw penetration is 5mm at all 4 locations.
4. The module connector height is 7.4 ± 0.13 [0.290± 0.005] plus standoff
~ 0.45mm ± 0.13 when mounted to a PCB.
5. Connector height with standoff is 8.00 ± 0.13 [0.315± 0.005]

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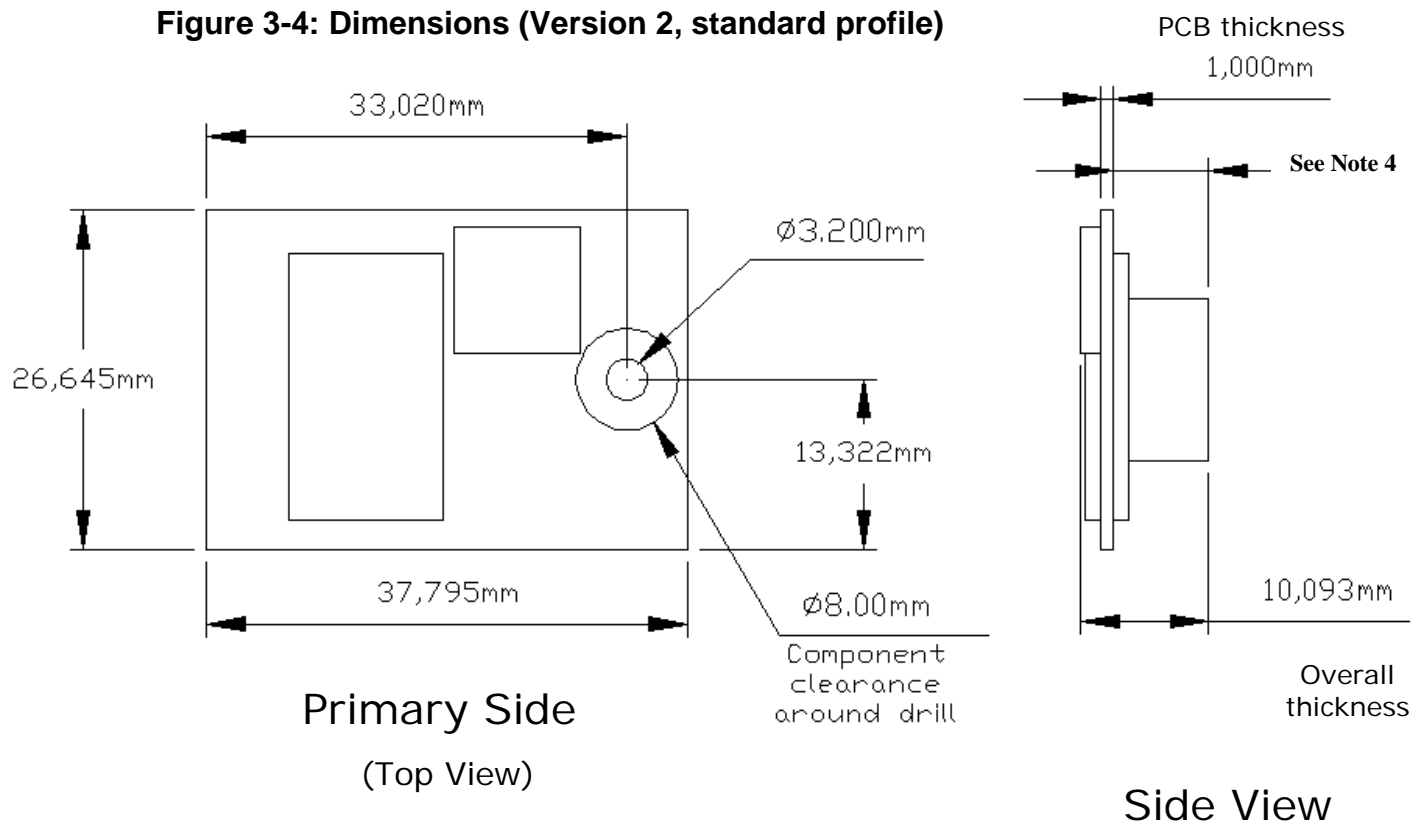
The dimensions of the eUSB (version 2) are based on the following
PCB #s: 1448, 1449

Figure 3-3: Dimensions (Version-2, low profile)



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Figure 3-4: Dimensions (Version 2, standard profile)



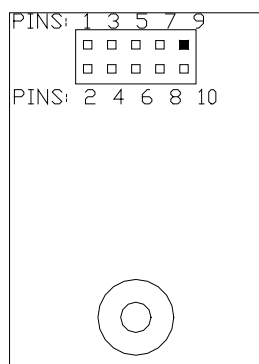
Notes:

1. Standard Profile Module Connector:
SAMTEC SSM-105-L-DV-LC-009-P-TR
Pitch: 2.54mm
2. Dimensions shown in millimeters
3. Max screw penetration is 5mm at all 4 locations.
4. The module connector height is
 7.4 ± 0.13 [0.290 ± 0.005]

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4 Pin and Signal Descriptions

Figure 4-1: Connector Pin Assignments



4.1 Signal and Power Description Tables

Table 4-1: eUSB Connector Pin Signal Definitions

Pin	Signal Name	Type	Description
1	VBUS	Power	3.3 or 5V power supply
2	NC	NC	Not connected
3	DM	I/O	USB 2.0 Data Negative Pin
4	NC	NC	Not connected
5	DP	I/O	USB 2.0 Data Positive Pin
6	NC	NC	Not connected
7	GND	Power	Ground
8	NC	NC	Not connected
9	N/A	Key	Polarization
10	#Activity	I/O	Status signal that indicates when the drive is busy. This signal may be used to drive a low current LED or other logic on the host to indicate drive status to the user or system. This signal is active low and has a 4mA drive strength.

Notes:

- * Available custom options: Pin 2 Chassis ground option; Pin 4 Hardware /WP; Pin 6 Hardware /Reset. Custom options available on locked BOMs only.

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5 Certifications and Compliance

Table 5-1: Device Certifications

Certification/Compliance	Description
RoHS	Viking Technology, Sanmina Corporation ("Viking") shall use commercially reasonable efforts to provide components, parts, materials, products and processes to customers that do not contain: (i) lead, mercury, hexavalent chromium, polybrominated biphenyls (PBB) and polybrominated diphenyl ethers (PBDE) above 0.1% by weight in homogeneous material or (ii) cadmium above 0.01% by weight of homogeneous material, except as provided in any exemption(s) from RoHS requirements (including the most current version of the "Annex" to Directive\ 2002/95/EC of 27 January, 2003), as codified in the specific laws of the EU member countries. Viking strives to obtain appropriate contractual protections from its suppliers in connection with the RoHS Directives.
EU WEEE Compliant	The Waste Electrical and Electronic Equipment Directive (WEEE Directive) is the European Community directive 2002/96/EC on waste electrical and electronic equipment (WEEE) which, together with the RoHS Directive 2002/95/EC, became European Law in February 2003, setting collection, recycling and recovery targets for all types of electrical goods.
Safety	All printed circuit boards (PCBs) have a flammability rating of UL94V-0.

6 References

- USB Specification, version 2.0

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